ĵ	Docket No.:				
	D	ECLARATION AN	D POWER OF ATTORN	VEY	
	As a below named inventor, I here	by declare that:		\$	
	My residence, post office and citize	enship are as stated below nex	to my name,		
	listed below) of the subject matter	claimed and for which a paten	t is sought on the invention entitledM	and joint inventor (if plural names are ULTILEVEL IMAGE GRID, the specification of which	
	[x] is attached hereto [] was filed on	as Application Serial (if applicable)	No and wa	
	I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.				
	I acknowledge the duty to disclose Federal Regulations, Section 1.56(a		o me to be material to patentability in	accordance with Title 37, Code of	
Per the first	I hereby claim foreign priority benefits under 35 U.S.C. 119(a)-(d) or 365 (b) of any foreign application(s) for patent or inventor's certificate, or 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below and have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or of any PCT international application having a filing date before that of the application on which priority is claimed.				
	Prior Foreign Application(s):			Filing Date	
-€-1 1-1	Number	Country		Day/Year	
i O L	3184/1999	Korea		01/1999	
C	I hereby claim the benefit under 35	5 U.S.C. 119(e) of any United S	itates provisional application(s) listed l	below.	
Li Li	Application Number(s):	Filing	Date (Month/Day/Year)		
ļ					
C)	I hereby claim the benefit under 35 U.S.C. 120 of any United States application(s), or 365(c) of any PCT international application designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application in the manner provided by the first paragraph of 35 U.S.C. 112, I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.				
	Prior U. S. Application or PCT Parent Number	Filing Date (Mo	nth/Day/Year) Pare	ent Patent Number (if applicable)	

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.



Post Office Address:



I hereby appoint the following attorney(s) and/or agent(s):Daniel Y.J. Kim, Registration No. 36,186 and Mark L. Fleshner, Registration No. 34,596; Carl R. Wesolowski, Registration No. 40,372, John C. Eisenhart, Registration No. 38,128, Rene A. Vazquez, Registration No. 38,647; Michael J. Cornelison, Registration No. 40,395; and Stuart I. Smith, Registration No. 42,159; and Carol L. Druzbick, Registration No. 40,287, all of

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with full power of substitution and revocation, to prosecute this application and to transact all busine connected therewith, and all future correspondence should be addressed to them.	£			
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Full name of sole or first inventor: Hyeon Jun KIM				
Inventor's signature:	Date: 200 1-24			
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Inventor's signature: RINDON	Date: 2000, 1.24			
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Full name of joint inventor(s): Jin Soo LEE	1511			
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